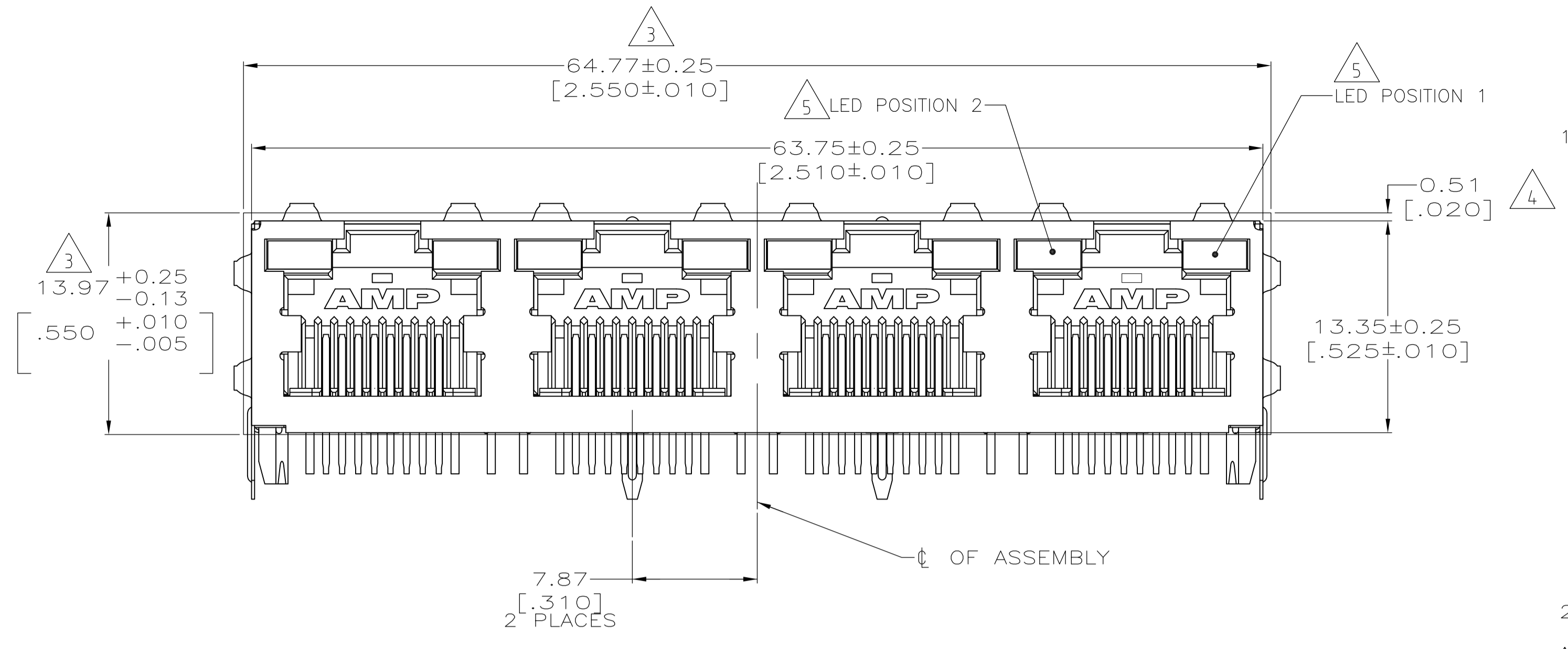
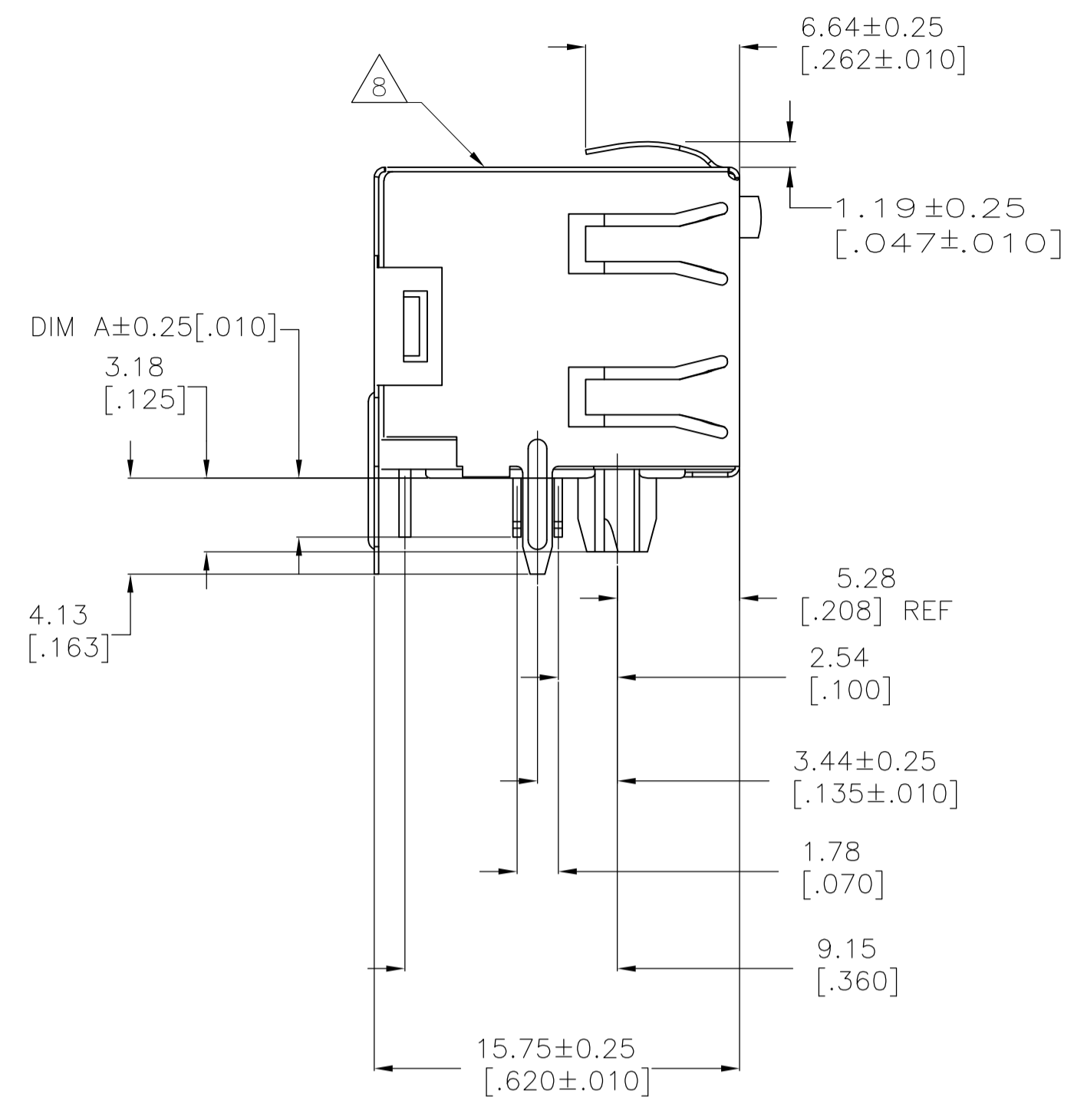
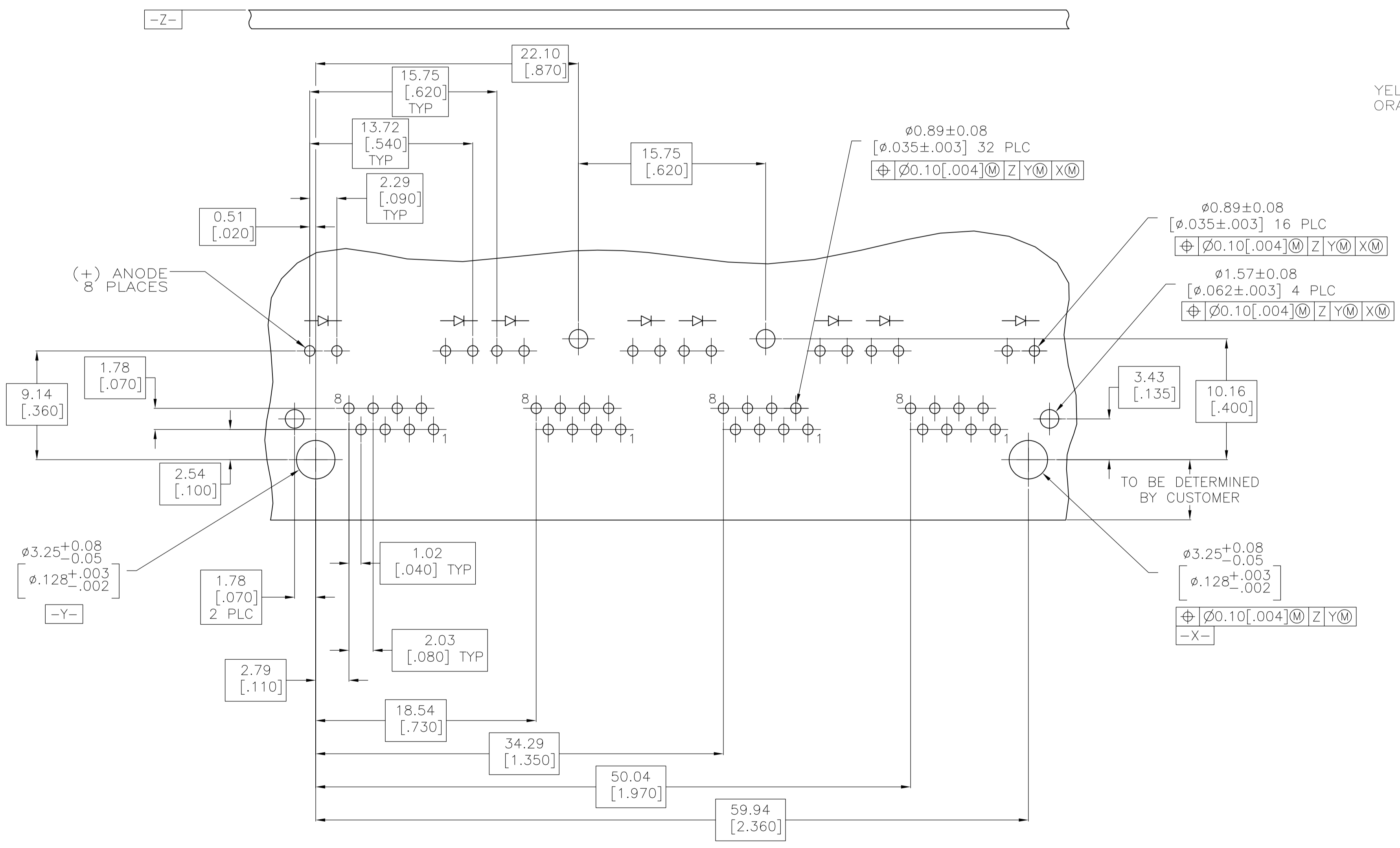


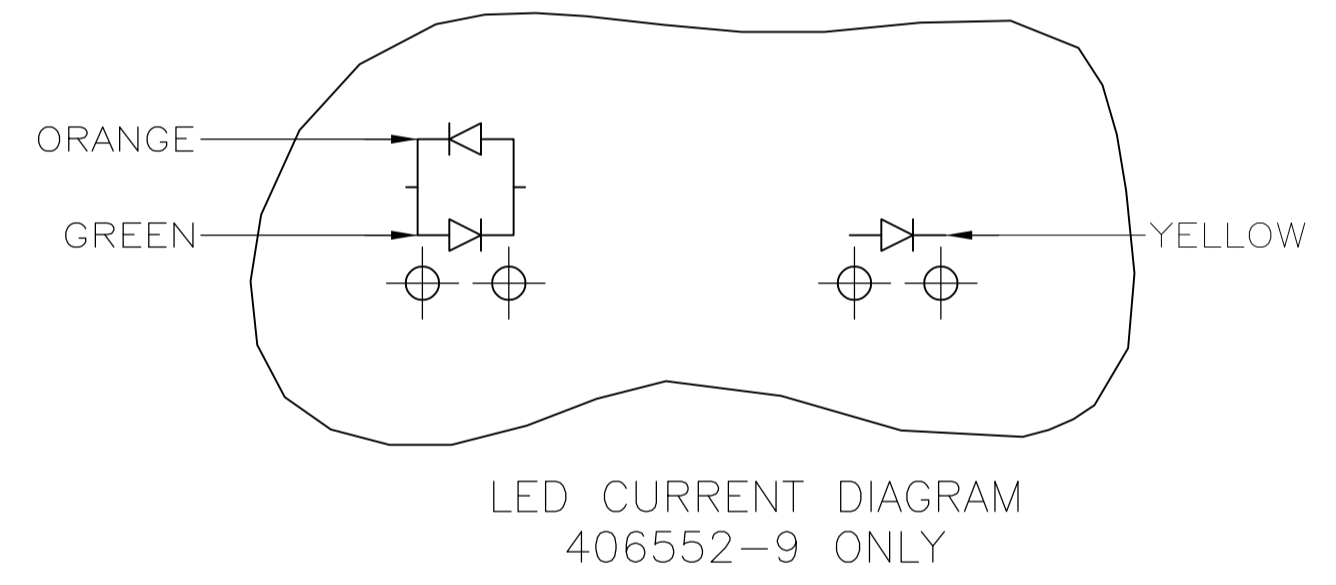
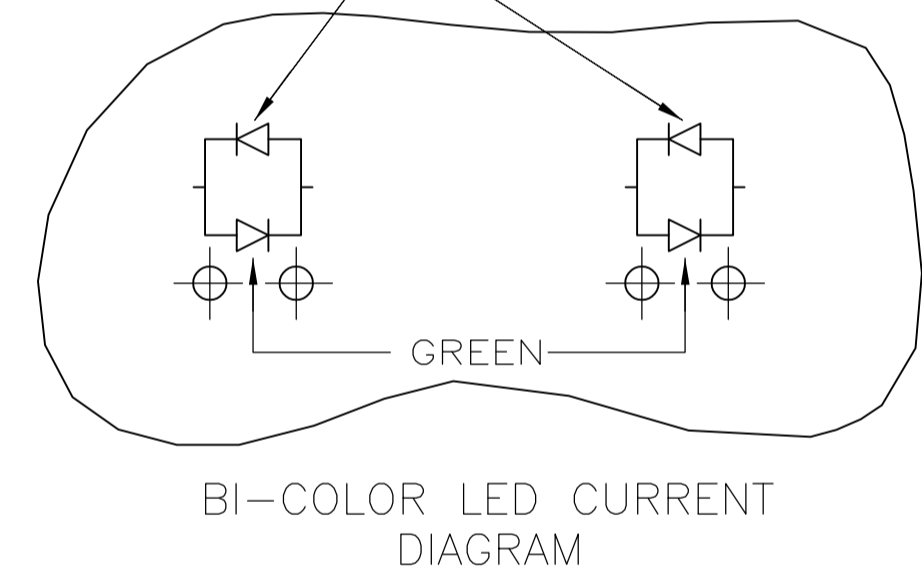
LOC		DIST		REVISIONS			
AA	00	F	LTR	DESCRIPTION	DATE	DMN	APVD
		K		ECO-07-022131	03NOV07	LAM	JW
		K1		REVISED PER ECO-09-021826	12SEP09	KK	AEG
		K2		REVISED ECR-10-006801	01APR10	AZ	SY



- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm[.000350] TIN/COPPER OVER 2.03µm[.000080] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- OBsolete PARTS: OBsolete CIS STREAMLINING PER D.RENAUD/D.SINISI
- MANUFACTURING DATE CODE:
 LOCATED APPROX. AS SHOWN.
 FIRST 2 DIGITS= LAST 2 DIGITS OF YEAR.
 NEXT 2 DIGITS= MANUFACTURING WORK WEEK.
 LAST DIGIT= DAY OF WEEK WITH SUNDAY=1.



YELLOW FOR 406552-8
 ORANGE FOR 406552-7



INDICATOR COLOR FOR EACH HOUSING	POSITION 2	POSITION 1	PART NUMBER
RED	GREEN	GREEN	1-406552-4
GREEN/RED	GREEN/RED	GREEN/RED	1-406552-3
YELLOW	GREEN	GREEN	1-406552-1
GREEN/ORANGE	YELLOW	YELLOW	406552-9
GREEN/YELLOW	GREEN/YELLOW	GREEN/YELLOW	406552-8
GREEN/ORANGE	GREEN/ORANGE	GREEN/ORANGE	406552-7
YELLOW	YELLOW	YELLOW	406552-6
GREEN	GREEN	GREEN	406552-5
GREEN	YELLOW	YELLOW	406552-4
YELLOW	-	-	406552-3
-	GREEN	GREEN	406552-2
YELLOW	GREEN	GREEN	406552-1

RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT.

THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION.

TYCO ELECTRONICS CORPORATION

INVERTED MODULAR JACK ASSEMBLY, 1X4, SHIELDED, PANEL GROUND, WITH LED

108-1163-4

114-2154

00779

406552

SCALE 4:1 SHEET 1 OF 1 REV K2

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[406552-8](#)